

### Features

- Single chip 80286 PC/AT Compatible Solution
- Supports CPU speeds to 16 MHz 0 or 1 Wait State
- Up to 4 Meg on-board Memory
- EMS with 4 Registers
- Supports 1M, 256K, and 64K devices in mixed modes
- Independent Clocking Source for the AT Bus
- Shadow RAM Support for System and Video BIOS in 16K blocks
- 384K Remapping in 64K blocks
- Hot Reset, Fast A20Gate
- HCMOS design for High Speed and Low Power Consumption
- Surface Mount Technology

### Description

The HT12, an IBM PC/AT compatible chip, supports the 80286 CPU at clock speeds to 16MHz. This highly integrated chip solution offers high performance and reliability, with low cost, minimal power consumption, and low board-space requirements. It differs from the HT11 by the addition of 4 EMS Registers and an EMS Software Driver.

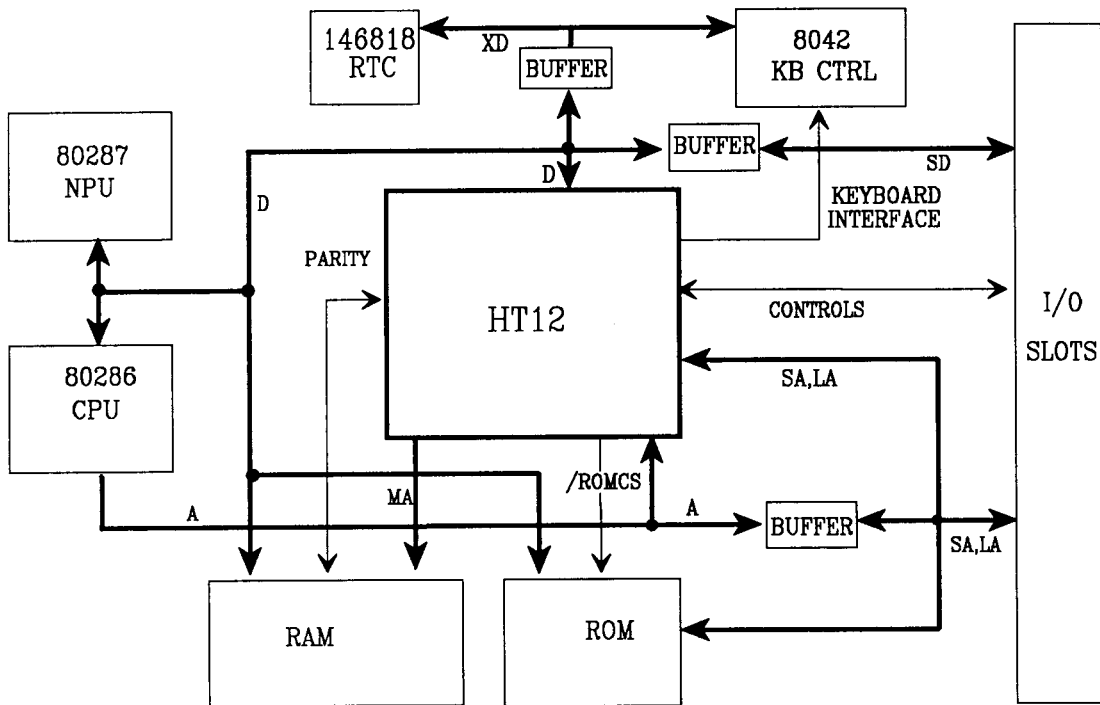
A fully PC/AT compatible system is implemented with this chip by adding a CPU/NPU, KBD CNTRL, RTC, BIOS, Memory and a few low cost TTL devices.

This chip supports 64K, 256K and 1M, x1 and x4, DRAMs in configurations up to 4 Meg. A 12.5MHz 0 wait-state system can

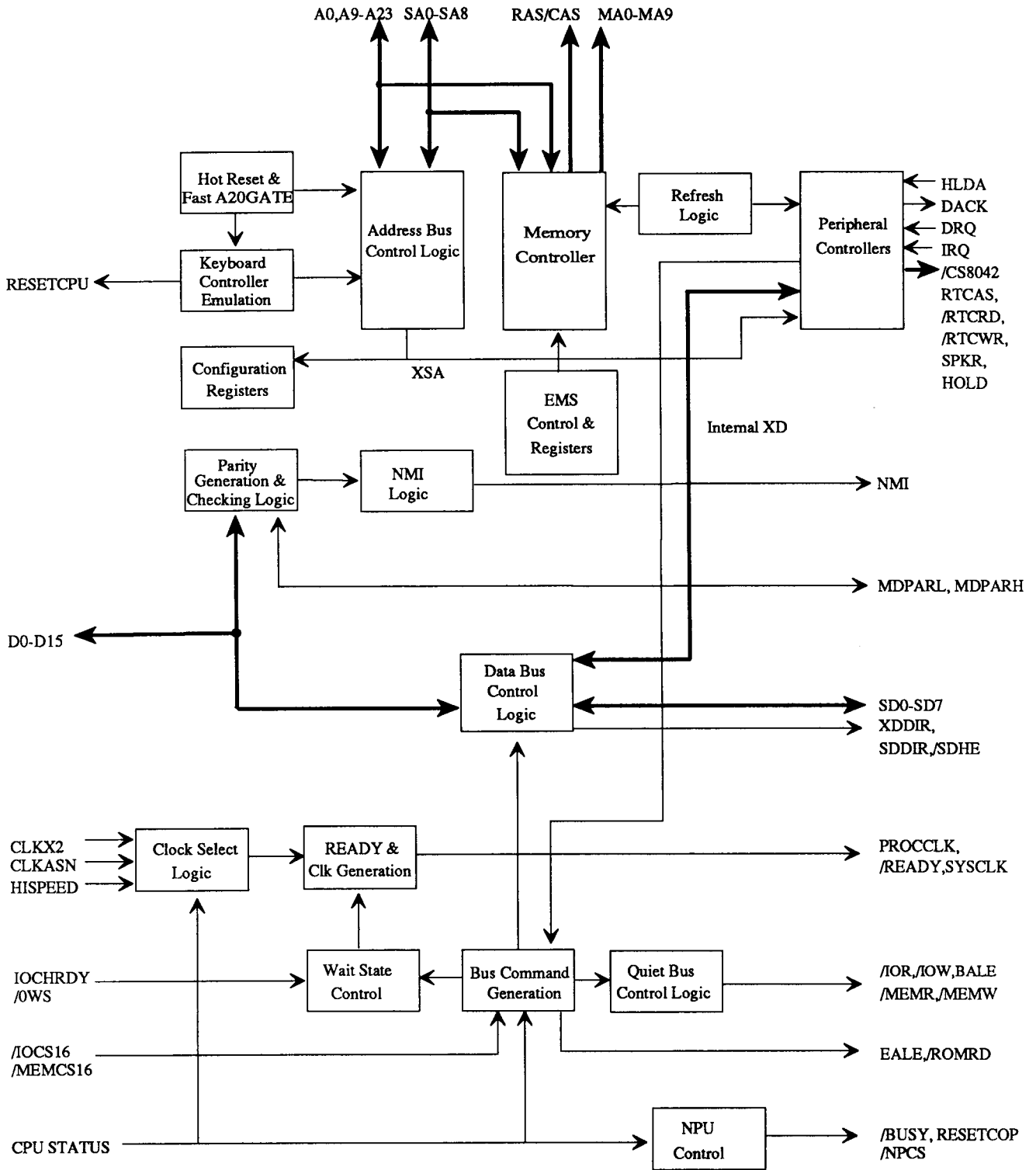
be implemented using 80ns DRAMs while a 10MHz 0 wait-state system requires 100ns DRAMs. The memory controller also supports the shadow RAM feature and the Split Memory option. The Split Memory option allows the System RAM located between 640K and 1M to be remapped above top of memory.

The HT12 contains CPU and peripheral support functions; including DMA controllers, a memory mapper, timer/counters, interrupt controllers, and a bus controller. This chip replaces board address buffers, data transceivers, memory drivers, parity generators and their support circuits. This chip is packaged in a 160 pin Flat Pack.

### System Board Block Diagram



# HT12 Internal Block Diagram



# HT12

## Functional Description

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The HT12 incorporates virtually all of the control circuits and "glue" logic of an AT architecture into a single CMOS VLSI chip. Circuits embedded in this device include: an 82284, 74612, 8284, 8254, two 8237s and two 8259s. The 82284 generates PROCCLK, /READY and /RESET for system use. It also provides all the CPU I/O command signals for memory, peripherals, and add-on boards. A 10-bit refresh counter produces the row address of memory during refreshes. The 74612 supplies DMA memory mapping addresses.

An 8284 uses the 14.318 MHz input clock to generate OSC and a 1.193 MHz base clock for the 8254 timer/counter. The 8254 provides 3 programmable timer/counters (channels 0 through 2). Channel 0 is used to generate IRQ 0 for the 8259A (Interrupt Controller). Channel 1 is used to generate Refresh Request cycles and Channel 2 is used for speaker tone generation.

The 8237s support Direct Memory Access, transferring 8-bit and 16-bit data between memory and I/O devices. The DMA controllers generate the correct commands to the CPU (Hold Request) and drive the appropriate bus command signals. The HT12 supports 2 8237 equivalent DMA controllers for a total of 7 DMA channels. The first DMA controller supports 8 bit peripherals and 8 or 16 bit memory using channels 0 through 3. The second DMA controller supports channels 4 through 7. Transfers between 16 bit peripherals and 16 bit memory use channels 5 through 7. Channel 4 is not available for use externally as it is used to cascade to the first DMA controller.

The two 8259s provide a total of 16 interrupt request lines (8 per 8259). IRQ0 is connected to the output of Channel 0 of the 8254 counter/timer. A second line, IRQ2 is used in cascading. IRQ1 is connected to the keyboard controller, IRQ8 is connected to the real time clock and IRQ13 is connected to the numeric processor. This leaves a total of 11 interrupt request lines that can be used externally. The 8259s issue signals to the CPU to initiate interrupt services.

The chip buffers data for the CPU(D0-15) and the system expansion data bus (SD0-7). In addition, address buffers for the System expansion bus (SA0-8), and the system board DRAMs (MA0-8) are provided. BALE is included to latch addresses from the CPU.

During memory read cycles, 16 RAM chips on the system board output MD to the HT11. Two additional RAM output MDPL (lower byte) and MDPH (upper byte). These 18 inputs are used in two 9-bit wide parity error detection circuits.

The RESETCPU signal on the HT12 is connected to the input of the 80286 processor. This signal can be generated from one of 3 sources. The first source is the PWRGOOD input signal. The next source is the /RC signal from the keyboard controller. The RESETCPU signal will also be generated if a shutdown command is generated from the 80286.

The HT12 can access 1M, x1 and x4, 256K and 64K DRAMs. The design encompasses zero or one wait state for memory operations and four wait states for I/O. The HT12 is internally programmed to insert, command delay based on the cycle type. Memory is configurable from 256K to 4 Mbytes.

The chip operates up to 16 MHz in the full commercial temperature range.

An independent clocking source for the AT bus clock is implemented. The clock input to the CLKASN (Asynchronous Clock) pin should be four times the desired bus clock speed. A 32MHz input to CLKASN will generate an 8MHz bus clock.

The chip converts 16-bit accesses for peripherals having only 8-bit wide buses; thus maintaining compatibility with the 8088 PC.

The coprocessor functions as an I/O device operating through I/O port addresses 0F8H, 0FAH, and 0FCH. The microprocessor sends OP codes and operands to the 80287 through these ports. The co-processor generates a BUSY signal to instruct the CPU that it is executing instructions. When this occurs the processor will generate a WAIT instruction to itself until the coprocessor is no longer BUSY. Once instructions are initiated, the CPU continues program execution with the co-processor.

## Functional Description

COMMAND DELAY, WAIT STATES BASED ON CYCLE TYPE					
COMMAND DELAY	LOCAL ROM READ		LOCAL RAM READ WRITE		
	NO		NO	NO	
COMMAND DELAY	AT BUS MEMORY		AT BUS I/O		AT BUS INTERRUPT ACKNOWLEDGE
	8 BIT	16 BIT	8 BIT	16 BIT	
COMMAND DELAY	YES	NO	YES	YES	YES
WAIT STATES	4	1	4	1	4

I/O Address Map		
Hex Range	Device Address	Part Number
000 - 0FF	Reserved for System board I/O	
000 - 01F	DMA Controller #1	8237A-5
020 - 03F	Interrupt Controller #1	8259A
040 - 05F	Timer	8254-2
060,062 - 06F	Keyboard Controller	8042
061	Port B Register,PPI	8255
070 - 07F	Real Time Clock, NMI (Non-interruptable Mask) bit	
080 - 08F	DMA Page Register	74LS612
090 - 091	Reserved	
092	Hot Reset and A20Gate	
093 - 09F	Reserved	
0A0 - 0BF	Interrupt Controller #2	8259A
0C0 - 0DF	DMA Controller #2	8237A-5
0F0	Clear Math Coprocessor Busy	
0F1	Reset Math Coprocessor	
0F2 - 0F7	Reserved	
0F8 - 0FF	Math Coprocessor	80287 only
1ED, 1EF	Configuration Registers	

**PORT B (8255) PPI Register, Address 61h**

**Data Written**

Bit 3 = 1	Disable NMI for IOCHCK(*)
Bit 2 = 1	Disable NMI for Memory Parity error
Bit 1	Speaker data
Bit 0 = 1	Enable Timer (8254) for speaker

**Data read back**

Bit 7 = 1	Memory Parity error
Bit 6 = 1	IOCHCK error(*)
Bit 5	Timer 2 (8254), output
Bit 4	REFRESH detect
Bit 3 = 1	NMI disabled, for IOCHCK(*)
Bit 2 = 1	NMI disabled for Memory Parity error(*)
Bit 1	Speaker data
Bit 0 = 1	Timer 2 (8254) for speaker enabled

NOTE(\*) Cleared on RESET

### Memory Configurations

The HT12 supports 8 different RAM configurations using combinations of 64K, 256K and 1M x1 or x4 DRAMs. The RAM configuration is determined by three configuration pins (DACK:2-0) on power up. The RAM configuration information is stored in the read/write System Configuration Register (index 04H and is overridable by software. The following is a table of valid RAM combinations.

Configuration	/DACK (Read)			Bank 0	Bank 1	Total
	2	1	0			
0	0	0	0	0K	0K	0K
1	0	0	1	256K	0K	512K
2	0	1	0	256K	64K	640K
3	0	1	1	256K	256K	1M
4	1	0	0	256K	1M	2.5M
5	1	0	1	1M	0K	2M
6	1	1	0	1M	1M	4M
7	1	1	1	-	-	Reserved

### BIOS Shadowing and Memory Relocation

The HT12 supports BIOS shadowing in 16K blocks in the range of C0000 to FFFFF. In the case that 1M of memory is installed, the HT12 also supports relocation of memory from address A0000 to address FFFFF that are not used in shadowing to above 1M. The following table shows the various shadowing and relocation combinations. Basically, contiguous memory above A0000 that are not used in shadowing can be relocated in 64K blocks. However, the combination of shadowing in only C0000-CFFFF and F0000-FFFFF can have both A0000-BFFFF and D0000-EFFFF relocated.

Shadow Range	Reloc Range	Memory Relocated
No shadowing	A0000-FFFFF	384K
C0000-	A0000-BFFFF	128K
D0000-	A0000-CFFFF	192K
E0000-	A0000-DFFFF	256K
F0000-	A0000-EFFFF	320K
C0000-CFFFF, F0000-FFFFF	A0000-BFFFF, D0000-EFFFF	256K

For shadowing operations, the BIOS should first select the required shadowing ranges in Shadow RAM Configuration Registers 1 to 2. When an address range is selected for shadowing, it becomes accessible and write only. This allows the BIOS to load ROM data into the shadow RAM. After all the shadow RAM are loaded, the BIOS enables the shadowing feature by setting the Shadow Enable bit in the Misc Feature Enable Register, Index 14H. Once shadowing is enabled, the shadow RAM becomes read only and all read cycles to the selected address ranges will be directed to the shadow RAM.

### **Hot Reset and A20Gate (Port 92H)**

The HT12 supports the Hot Reset and A20Gate functions as defined in the PS/2 Technical Reference. Both functions can be used in conjunction with the keyboard controller functions.

### **Independent Bus Clock**

HT12 supports two independent clock sources. It normally runs off the high speed clock (CLKX2), but switches to the asynchronous clock (CLKASN) for off-board memory accesses or I/O accesses such that AT bus timing requirements are satisfied. The AT bus clock (SYSCLK) is maintained constant at 1/4 the asynchronous clock (CLKASN).

### **Address and Data Bus**

The HT12 uses a modified address and data bus design. The address bus is made up of the upper 15 address signals from the CPU and the lower 9 address signals from the SA bus. The remaining portion of the SA bus and the LA bus are generated externally using TTL latches and buffers. The direct use of CPU high order addresses allows the chip to perform fast DRAM accesses. All peripherals normally connected to XA should be connected to A and SA.

The data bus consists of the 16 bit CPU D bus and the lower 8 bits of the SD bus. The upper 8 bits of the SD bus and the XD bus are generated externally using TTL buffers. The MD bus is eliminated in the design. On-board DRAMs and BIOS EPROMs are both tied to the CPU local D bus.

To generate MA for the row addresses in time for RAS, the row addresses must come directly from the CPU address bus especially when running at 16MHz. The HT12 must include address lines A(23:9) in its address bus and use the remaining pins to generate SA(0:7). Since only a portion of the SA bus is generated by the HT12, five TTL latches/buffers are used to generate the remaining SA and LA signals. Furthermore, although the column address timing is not as critical as the row address timing, to provide proper column MA, the SA signals must be latched with an Early ALE signal.

### **Memory Controller**

The memory controller consists of five major sub-blocks:

#### **ECONTROL**

The ECONTROL block is used to generate the early control signals EALE, /EMEMR and /EMEMW. The /EMEMR and /EMEMW signals are synchronized to the processor clock for master cycles. Since A1 is not directly accessible, EALE is generated for CPU shutdown/halt cycle as well, so that A1 can be accessed via SA1.

**PARGEN**

Due to the tight RAM access time, RAM data are not valid until the very end of a RAM read. To ensure sufficient time for parity generation, parity generation logic is required to allow separate read and write path for the parity generation. Moreover, on a RAM read, the data are latched to provide more time for the parity to be generated.

**ADDRTRAN**

To support mixed 64K/256K/1M DRAMs, BIOS shadowing, EMS and memory relocation, an address translating and decoding block ADDRTRAN is required. Given the RAM configuration, the ADDRTRAN block performs address translations to relocate unused memory in segments A000-F000 to the top of memory and provides output signals to indicate shadow RAM accesses and relocated memory accesses.

**RAMCONTROL**

The RAMCONTROL logic is a state machine that generates the necessary RAS, CAS and WE signals. It provides 10MHz to 16MHz accesses in either 0 or 1 wait state.

**MAGEN**

The MAGEN block generates the row and column addresses for the DRAM. It supports mixed 64K, 256K and 1M DRAM types.



Nine read/write registers are available in the P11. They consist of eight configuration registers and a Hot reset and Gate A20 control register.

The configuration registers are accessed through the two I/O ports at locations 1ED and 1EF. Port 1ED serves as an index register in determining which configuration register is accessed at port 1EF. To access a configuration register, the corresponding index must first be written into the index register at location 1ED. The index register and all configuration registers are read/write register. The status registers are Read only.

The Hot reset and Gate A20 control register is a partial emulation of the PS/2 Port 92H. It supports the Hot Reset and the Gate A20 functionalities as defined in the PS/2 Technical Reference.

### INDEXED CONFIGURATION REGISTERS

Index Port: 1ED Data Port: 1EF	
<u>Index</u>	<u>Register</u>
10H	System configuration Register
11H	Reserved
12H	Shadow RAM configuration Register 1
13H	Shadow RAM configuration Register 2
14H	Misc Feature Enable Register
15H	Misc Status Register
16H	Extended Information Register
17H	Revision Information Register
18H	Top of Memory Register
19H	EMS Configuration Register
20H	EMS Page Register 0
21H	EMS Page Register 1
22H	EMS Page Register 2
23H	EMS Page Register 3

### I/O MAPPED REGISTERS

<u>Address</u>	<u>Register</u>
92H	Hot Reset and A20 Gate Control Register

NOTE: When modifying a configuration register **always** read the configuration register first. Change only the bits that must be changed, then write the data back to the register. This will insure compatibility with future design features.

**HT12**  
**Register Description**

**SYSTEM CONFIGURATION REGISTER (INDEX: 10H)**

Bit	7	6	5	4	3	2	1	0
		WS CTRL1	WS CTRL0	0 WS MEM	BUS SPEED	RAM SEL2	RAM SEL1	RAM SEL0

Bits	Access	Default	Description (As Inputs during Power On Reset)																																				
2-0	R/W	DACK2-0	RAM Configuration  <table style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="text-align: left;">RAMSEL &lt;2:0&gt;</th> <th style="text-align: left;">Bank 0 RAM Type</th> <th style="text-align: left;">Bank 1 RAM Type</th> <th style="text-align: left;">Total Size</th> </tr> </thead> <tbody> <tr> <td>0</td> <td>0K</td> <td>0K</td> <td>0K</td> </tr> <tr> <td>1</td> <td>256K</td> <td>0K</td> <td>512K</td> </tr> <tr> <td>2</td> <td>256K</td> <td>64K</td> <td>640K</td> </tr> <tr> <td>3</td> <td>256K</td> <td>256K</td> <td>1M</td> </tr> <tr> <td>4</td> <td>256K</td> <td>1M</td> <td>2.5M</td> </tr> <tr> <td>5</td> <td>1M</td> <td>0K</td> <td>2M</td> </tr> <tr> <td>6</td> <td>1M</td> <td>1M</td> <td>4M</td> </tr> <tr> <td>7</td> <td>-</td> <td>-</td> <td>-</td> </tr> </tbody> </table>	RAMSEL <2:0>	Bank 0 RAM Type	Bank 1 RAM Type	Total Size	0	0K	0K	0K	1	256K	0K	512K	2	256K	64K	640K	3	256K	256K	1M	4	256K	1M	2.5M	5	1M	0K	2M	6	1M	1M	4M	7	-	-	-
RAMSEL <2:0>	Bank 0 RAM Type	Bank 1 RAM Type	Total Size																																				
0	0K	0K	0K																																				
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3	256K	256K	1M																																				
4	256K	1M	2.5M																																				
5	1M	0K	2M																																				
6	1M	1M	4M																																				
7	-	-	-																																				
3	R/W	DACK3	AT Bus Speed 1: Low Speed on I/O 0: Full Speed																																				
4	R/W	DACK5	0 Wait State Memory 1: 0 wait state memory 0: 1 wait state memory																																				
6-5	R/W	DACK6-7	Wait State Control* WSCTRL (1:0) 0 0: 1 extra Wait State for EMS + relocation cycles 0 1: 1 extra Wait State for EMS cycles only 1 0: 1 extra Wait State for Relocation cycles only 1 1: No extra Wait State																																				
7	R/W	TC	Reserved																																				

**Special Note:** the DACK and TC lines are used as configuration inputs during power up reset.

\*Wait state control can be used to add an extra wait state for the above cycle types. When a memory cycle of the selected type occurs, the cycle will not be started until one wait state later. For example, if WSCTRL <1:0> is set to 0, EMS cycles that require memory relocation would have an extra wait state inserted; that is, a normally 0 wait state cycle would become 1 wait state and a normally 1 wait state cycle would become 2 wait state. This allows additional RAM address setup time for high speed operations.

**SHADOW RAM CONFIGURATION REGISTER 1 (INDEX: 12H)**

Bit	7	6	5	4	3	2	1	0
	DC000 DFFFF	D8000 DBFFF	D4000 D7FFF	D0000 D3FFF	CC000 CFFFF	C8000 CBFFF	C4000 C7FFF	C0000 C3FFF

Bits	Access	Default	Description
0	R/W	0	Enable Shadowing C0000-C3FFF 1: Enable 0: Disable
1	R/W	0	Enable Shadowing C4000-C7FFF 1: Enable 0: Disable
2	R/W	0	Enable Shadowing C8000-CBFFF 1: Enable 0: Disable
3	R/W	0	Enable Shadowing CC000-CFFFF 1: Enable 0: Disable
4	R/W	0	Enable Shadowing D0000-D3FFF 1: Enable 0: Disable
5	R/W	0	Enable Shadowing D4000-D7FFF 1: Enable 0: Disable
6	R/W	0	Enable Shadowing D8000-DBFFF 1: Enable 0: Disable
7	R/W	0	Enable Shadowing DC000-DFFFF 1: Enable 0: Disable

Register Description

**SHADOW RAM CONFIGURATION REGISTER 2 (INDEX: 13H)**

Bit	7	6	5	4	3	2	1	0
	FC000 FFFFF	F8000 FBFFF	F4000 F7FFF	F0000 F3FFF	EC000 EFFFF	E8000 EBFFF	E4000 E7FFF	E0000 E3FFF

Bits	Access	Default	Description
0	R/W	0	Enable Shadowing E0000-E3FFF 1: Enable 0: Disable
1	R/W	0	Enable Shadowing E4000-E7FFF 1: Enable 0: Disable
2	R/W	0	Enable Shadowing E8000-EBFFF 1: Enable 0: Disable
3	R/W	0	Enable Shadowing EC000-EFFFF 1: Enable 0: Disable
4	R/W	0	Enable Shadowing F0000-F3FFF 1: Enable 0: Disable
5	R/W	0	Enable Shadowing F4000-F7FFF 1: Enable 0: Disable
6	R/W	0	Enable Shadowing F8000-FBFFF 1: Enable 0: Disable
7	R/W	0	Enable Shadowing FC000-FFFFF 1: Enable 0: Disable

## Register Description

## MISC FEATURE ENABLE REGISTER (INDEX: 14H)

Bit	7	6	5	4	3	2	1	0
			MEM PAR DIS	ENABLE 64K BIOS	256K- 640K	RELOC ENABLE	SHADOW ENABLE	QUIET BUS

Bits	Access	Default	Description
0	R/W	1	Quiet Bus Enable 1: Enable 0: Disable
1	R/W	0	Enable Shadowing Function 1: Enable 0: Disable
2	R/W	0	Enable Relocation Function 1: Enable 0: Disable
3	R/W	1	Enable Memory 40000H-9FFFFH 1: Enable 0: Disable
4	R/W	0	Enable 64K BIOS This option selects the size of the system BIOS. When enabled, the system BIOS occupies only the 64K addressing space F000:0000-F000:FFFF. When disabled, the system BIOS occupies the normal AT compatible 128K addressing space E000:0000-F000:FFFF. 1: Enable 0: Disable
5	R/W	0	Memory Parity Disable This option allows memory parity to be disabled regardless of the port 61H bit 2 setting. 0: Don't disable parity 1: Disable Parity
6-7	R/W		Reserved Must be set to 0 by BIOS on power up.

**HT12**  
**Register Description**

**MISC STATUS REGISTER (INDEX: 15H)**

Bit	7	6	5	4	3	2	1	0
	0	0	0	0	0	0	NMI EN	8042 A20GATE

Bits	Access	Default	Description
0	R		8042 A20Gate 1: A20 Enabled 0: A20 Forced Low
1	R		NMI Enable Status 1: NMI Enabled 0: NMI Disabled (inverse of data written at Port 70)
2-7	R	0	Reserved

**EXTENDED INFO REGISTER (INDEX: 16H)**

Bit	7	6	5	4	3	2	1	0
	0	0	0	0	0	0	0	0

Bits	Access	Default	Description
0-7	R	0	Reserved

**REVISION INFO REGISTER (INDEX: 17H)**

Bit	7	6	5	4	3	2	1	0
	CHIP ID	CHIP ID	CHIP ID	CHIP ID	REV	REV	REV	REV

Bits	Access	Default	Description
3-0	R		Revision Number 0= Rev. A
7-4	R	1	HT12 Identification Number

**HT12**  
**Register Description**

**TOP OF EXTENDED MEMORY REGISTER (INDEX: 18H)**

Bit	7	6	5	4	3	2	1	0
			TA 21	TA 20	TA 19	TA 18	TA 17	TA 16

Bits	Access	Default	Description
0-5	R/W	03FH	<p><b>Top of Extended Memory</b> This register specifies the top of extended memory with a granularity of 64K. Extended memory address must be less than or equal to the Top of Memory setting. The memory above the Top of Extended Memory and below the total available memory can be used for EMS. This register defaults to 03FH (No EMS memory). On power up, the BIOS should set this register to reflect the actual top of extended memory.</p>
6-7			Reserved

Register Description

**EMS Configuration Register (Index: 19H)**

Bit	7	6	5	4	3	2	1	0
	EMS EN	PAGE ADDR2	PAGE ADDR1	PAGE ADDR0	PAGE 3 EN	PAGE2 EN	PAGE1 EN	PAGE0 EN

Bits	Access	Default	Description
0	R/W	0	<p>Page Enable 0</p> <p>1: Enable 0: Disable</p> <p>If the Global EMS Enable is on (1), the enable bit associated with each EMS page enables or disables the corresponding page.</p>
1	R/W	0	<p>Page Enable 1</p> <p>1: Enable 0: Disable</p>
2	R/W	0	<p>Page Enable 2</p> <p>1: Enable 0: Disable</p>
3	R/W	0	<p>Page Enable 3</p> <p>1: Enable 0: Disable</p>
4-6	R/W	0	<p>EMS Pages Starting Address</p> <p>0 (000): C000:0000</p> <p>1 (001): C400:0000</p> <p>2 (010): C800:0000</p> <p>3 (011): CC00:0000</p> <p>4 (100): D000:0000</p> <p>This starting address specifies the address of EMS page 0. EMS page 1 to 3 follow consecutively in 16K increments.</p>
7	R/W	0	<p>Global EMS Enable</p> <p>1: Enable 0: Disable</p> <p>If the Global EMS Enable is off (0), all EMS pages are disabled regardless of their individual enable bit.</p>

**EMS PAGE REGISTERS 0-3 (INDEX: 20H-23H)**

Bit	7	6	5	4	3	2	1	0
	PA 21	PA 20	PA 19	PA 18	PA 17	PA 16	PA 15	PA 14

Bits	Access	Default	Description
0-7	R/W		Translated EMS address lines



**HT12**  
**Register Description**

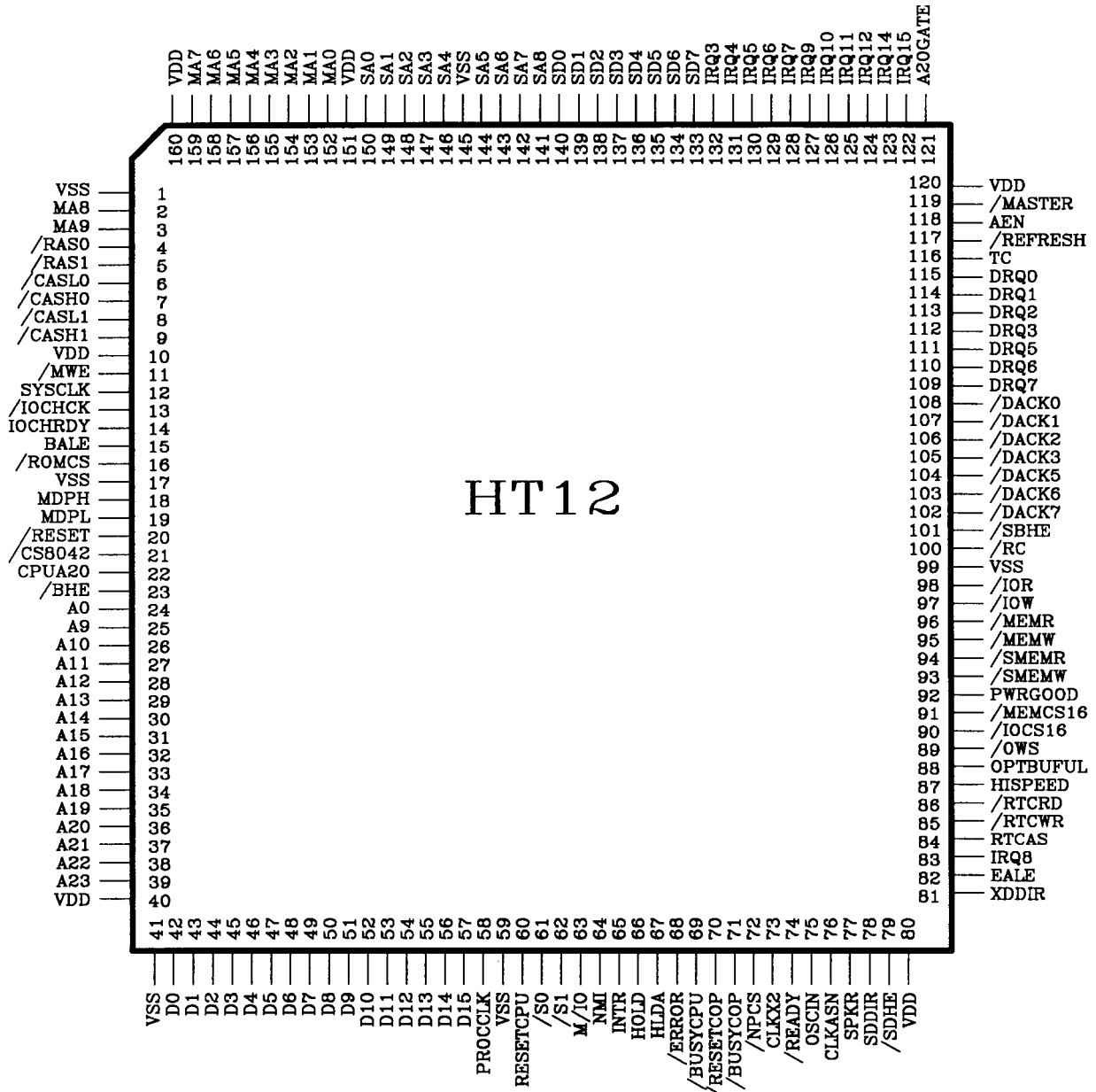
**PORT 92H (HOT RESET AND GATE A20)**

Bit	7	6	5	4	3	2	1	0
	0	0	0	0	0	0	GATE A20	HOT RESET

Bits	Access	Default	Description
0	R/W	0	<p><b>Hot Reset</b> This function provides an alternate means to reset the CPU. When this bit is set high, it triggers an alternate reset pulse to the reset logic. The reset occurs after a minimum of 6.72us and the entire reset operation takes 13.4us. When the reset bit is set to 1, it remains set until cleared by the BIOS.</p> <p style="margin-left: 40px;">1: Reset 0: Clear reset</p>
1	R/W	0	<p><b>Gate A20</b></p> <p style="margin-left: 40px;">1: A20 active 0: A20 inactive</p>
2-7	R	0	<b>Reserved</b>

# HT12

## Pin Diagram



## HT12 Pin Description

Pin Symbol	Pin Numbers	Pin Type	Pull Up/Dn*	Description
A0	24	I	PU	Address line 0: Address input from CPU.
A9-23	25-39	I/O		Address lines: These are bi-directional address lines that input from the CPU and the I/O slot and output from the DMA controllers and the memory mapper.
A20GATE	121	I		Gates address from 80286: If CPUHLDA=0, the 80286 CPU is driving the address bus. When A20GATE is high, the upper address bit (CPUA20 input) drives the A20 pin directly, when low the A20 output is forced low regardless of the state of CPUA20.
AEN	118	O		Address Enable: This signal is used to disconnect the microprocessor and other devices from the I/O channel to allow DMA transfers to take place. When AEN is high, the DMA controller drives the address bus, data buses, and read/write command lines for both memory and I/O.
BALE	15	O		Buffered Address Latch Enable: This signal is provided by the 82288 bus controller and is used to latch valid addresses and memory decodes from the microprocessor. It is used by the I/O channel as an indicator of a valid microprocessor or DMA address (when used with AEN). BALE is forced high during DMA cycles.
/BHE	23	I	PU	Byte High Enable: A low level enables the high byte D15-8 of the data bus.
/BUSYCOP	71	I	PU	Connect /BUSY out of the 80287 to this /BUSYCOP input. When the math co-processor is working it drives this input pin low, which in turn forces the /BUSYCPU output low and stops 80286 program execution on WAIT and some ESC instructions until /BUSYCPU becomes inactive (high).

\* Indicates Internal Resistor

## HT12 Pin Description

Pin Symbol	Pin Numbers	Pin Type	Pull Up/Dn*	Description
/BUSYCPU	69	O		Connect /BUSYCPU output to the /Busy input of the 80286 CPU. A low level on this pin indicates the math co-processor (80287) is executing a command. Interrupts are honored by the 80286 while this input is low. /BUSY latched by /ERROR. (See /Error)
/CASH0, /CASH1	7,9	O		Column Address Strobe High order byte: These control 2 banks of DRAMS.
/CASL0, /CASL1	6,8	O		Column Address Strobe Low order byte: These control 2 banks of DRAMS.
CLKASN	76	I	PU	Asynchronous AT Bus clock source. The input frequency should be four times the required bus frequency.
CLKX2	73	I	PU	CLKX2: Drive this clock input at twice the desired processor clock (PROCCLK) frequency.
CPUA20	22	I	PU	Address 20 from the 80286. This input drives the A20 output pin, if CPUHLDA=0 and A20GATE=1.
/CS8042	21	O		Chip Select 8042: is used to drive the /CS input of the 8042 keyboard controller. This signal is low when the address decode is in the range of 60-6F (hex). used to drive the /CS input of the 8042 keyboard controller.
D(0-15)	42-57	I/O	PU	Bi-directional Data Bus: Data to/from the 80286.
/DACK (0-3,5-7)	108-105 104-102	I/O	PU	DMA ACKnowledge: These are active low signals used to acknowledge DMA requests (DRQ0-3 5-7) from peripherals on the I/O expansion slots. These pins are also read as configuration pins on power up.

\* Indicates Internal Resistor

## HT12 Pin Description

Pin Symbol	Pin Numbers	Pin Type	Pull Up/Dn*	Description
DRQ (0-3,5-7)	115-112 111-109	I	PD	These asynchronous channel requests are used by peripheral devices and the I/O channel microprocessors to gain DMA service, or control of the system. They are prioritized with DRQ0 having the highest priority and DRQ7 having the lowest. Each signal should be held high until the corresponding DMA Request Acknowledge (/DACK) signal goes active (low). DRQ0-3 govern 8 bit DMA transfers, DRQ5-7 govern 16-bit transfers.
EALE	82	O		Early Address Latch Enable latches SA1-19.
/ERROR	68	I	PU	/ERROR: Connect /ERROR from the 80287 to this input. A low level indicates the math co-processor has an unmasked error condition. The HT12 responds by latching /BUSY and setting IRQ13.
HISPEED	87	I	PU	High SPEED: When high, PROCCLK (the processor clock) speed is equal to CLKX2 . When low, PROCCLK is equal to half of CLKASN.
HLDA	67	I	PD	HoLD Acknowledge: The 80286 drives this high, when it relinquishes control of the system. This forces the A20 output tri-state.  With CPUHLDA low, a low on A20GATE forces A20 low. A high on A20GATE passes CPUA20 through to pin A20.
HOLD	66	O		CPU Hold to 80286.
INTR	65	O		INTerrupt Request: Interrupt request signals from the HT12 to the 80286. A high on this output requests an interrupt from the 80286 CPU.

\* Indicates Internal Resistor

## HT12 Pin Description

Pin Symbol	Pin Numbers	Pin Type	Pull Up/Dn*	Description
/IOCHCK	13	I	PU	I/O CHannel ChecK: A low on this input indicates that there is an uncorrectable system error. It provides the system board with parity (error) information about memory or devices on the I/O channel. This causes the NMI (Non-Maskable Interrupt) output to become active (high), and interrupts the 80286 CPU.
IOCHRDY	14	I	PU	I/O CHannel ReaDY: Held low by the I/O or memory devices to lengthen the cycles. Any slow device using this line should drive it low immediately upon detecting its valid address and a Read/Write command. This signal should not be held low for more than 2.5 microseconds, or memory data may be lost due to inadequate refresh.
/IOCS16	90	I	PU	I/O Chip Select 16: A low indicates a 16-bit, 1 wait state I/O cycle, data transfer on the I/O bus. This signal should be driven by an open collector or tri-state driver capable of sinking 20mA.
/IOR	98	I/O	PU	I/O Read: When low, instructs an I/O device to drive its data onto the data bus. It is driven by the microprocessor or DMA controller, either resident in the system or on the I/O channel.
/IOW	97	I/O	PU	I/O Write: When low, instructs an I/O device to read the data on the data bus. It may be driven by any microprocessor or DMA controller in the system or on the I/O channel.
IRQ(3-7, 9-12,14,15)	132-128 127-124 123,122	I	PU	Interrupt ReQuest: These pins signal the microprocessor that an I/O device needs attention. An interrupt request is generated when an IRQ line is raised from low to high. The line must be held high until the microprocessor acknowledges the interrupt request (Interrupt Service routine.) IRQ3 has the highest priority interrupt, IRQ15 the lowest.
/IRQ8	83	I	PU	This input is driven by the Real Time Clock interrupt output. (Note that Interrupt Request 8 is active low unlike the other Interrupt Requests).

\* Indicates Internal Resistor

## HT12 Pin Description

Pin Symbol	Pin Numbers	Pin Type	Pull Up/Dn*	Description
MA(0-9)	152-159,2,3	O		Memory Address bus: Address lines of the system RAM.
/MASTER	119	I	PU	/MASTER: This signal is used with a DRQ line to gain control of the system. A processor or DMA controller on the I/O channel issues a DRQ to a DMA channel in cascade mode and receives a /DACK. Upon receiving the /DACK, an I/O microprocessor pulls /MASTER input low, which will allow it to control the system address, data, and control lines ( a condition known as tri-state). After this signal is pulled low the I/O microprocessor must wait one system clock period before driving the address and data lines and two clock periods before issuing a Read/Write command. If this signal is held low for more than 15 microseconds, the system memory may be lost because of a lack of refresh.
MDPL MDPH	19,18	I/O	PU	Memory Data Parity: Low (0) and high (1) bytes: When data is written to RAM or read from RAM its parity value is calculated.
/MEMCS16	91	I	PU	MEMory Chip Select 16: A low signals the system board that the present data transfer is a 1 wait-state, 16 bit, memory cycle. This signal should be driven by open collector or tri-state driver capable of sinking 20mA.
/MEMR	96	I/O	PU	MEMory Read: Output is low during a memory read cycle. This signal instructs the memory devices to drive data onto the data bus. It can be driven by any microprocessor or DMA controller in the system. When a microprocessor on the I/O channel drives this signal it must have the address lines valid on the bus for 1 system clock period before driving /MEMR active. Not active during local memory cycles.

\*Indicates Internal Resistor

## HT12 Pin Description

Pin Symbol	Pin Numbers	Pin Type	Pull Up/Dn*	Description
/MEMW	95	I/O	PU	MEMory Write: Output is low during a memory write. This signal instructs the memory devices to store the data present on the data bus. It is active during all memory read cycles and can be driven by any microprocessor or DMA controller in the system. When driven by a microprocessor on the I/O channel the address lines on the bus must be valid for one system clock period before driving the signal active. This is tri-stated when /MASTER is low. Not active during local memory cycles.
M/IO	63	I	PU	Memory I/O from the 80286: If high during status cycle (TS), a memory cycle is in progress; if low, an I/O cycle is occurring. Tri-state when the 80286 is in Hold Acknowledge. (See HLDA)
/MWE	11	O		Memory Write Enable to the DRAM
NMI	64	O		Non-Maskable Interrupt: A high level forces the 80286 CPU to unconditionally execute an interrupt routine.
/NPCS	72	O		Numeric Processor Chip Select: A low signal enables the math co-processor chip. This pin is connected to /NPS1 of the 80287.
OPTBUFUL	88	I	PD	OutPut Buffer Full: Input from P24 of the keyboard controller. Setting this pin high activates the internal IRQ1. This causes an INTR to the 80286 CPU indicating the keyboard buffer is full.
OSCIN	75	I	PU	14.318 MHz input.
PROCCLK	58	O		PROCeSSor CLocK: this output supplies the clock signal for the 80286 and 80287 chips. It drives CLK on the 80286, and CLK286 on the 80287 math processor. Rate determined by HISPEED.

\*Indicates Internal Resistor



## HT12 Pin Description

Pin Symbol	Pin Numbers	Pin Type	Pull Up/Dn*	Description
PWRGOOD	92	I	PU	PoWeRGOOD: When low, it resets the entire system. A Schmitt Trigger buffers the input pin.
/RAS0, /RAS1	4,5	O		Row Address Strobe: Selects RAM bank 0 or 1 RAS controls.
/RC	100	I	PU	Reset CPU: When driven low by the keyboard controller (P20), the 80286 CPU is reset.
/READY	74	O		/READY: A low level tells the 80286 CPU that the current bus cycle is near completion.
/REFRESH	117	I/O	PU	/REFRESH: indicates that the current cycle is a memory refresh cycle. /REFRESH is an open drain output and can be driven by a microprocessor or another bus master on the I/O channel.
/RESET	20	O		/RESET: an active low output used to reset the system logic at power-up or low-line voltage.
RESETCOP	70	O		RESET CO-Processor: A low-to-high transition resets the 80287 co-processor. This should be held high for 4 system 80287 clocks (PROCCLK).
RESETCPU	60	O		RESET CPU: A low-to-high transition resets the 80286 CPU during powerup, keyboard reset, and shut down. The rising edge resets the CPU, if the pin is held high for 16 clock cycles.
/ROMCS	16	O		ROM Chip Select
RTCAS	84	O		Real Time Clock Address Strobe: When low, this latches the RAM address for read/write operations. Connect to AS on RTC.

\* Indicates Internal Resistor

## HT12 Pin Description

Pin Symbol	Pin Numbers	Pin Type	Pull Up/Dn*	Description
/RTC RD	86	O		Real Time Clock ReaD: When low data is read from the RTC. Connect to /DS pin of RTC.
/RTC WR	85	O		Real Time Clock WRite: When low data is written to the RTC. Connect to R/W pin of RTC.
/S0, /S1	61,62	I	PU	CPU Status bits 0,1: These pins convey the current 80286 CPU status to the internal 82288 bus controller (mega function). When /S0, /S1, INTA, are low and M/I/O is high a shutdown or halt of the 80286 occurs. If A1=1, the CPU halts. If A1=0 the system shuts down.
SA(0-8)	150-146, 144-141	I/O	PU	System Address bus: Bi-directional address bus for the expansion bus. They are gated on the system bus when BALE is high and are latched on the falling edge of BALE during DMA. These signals are generated by the microprocessor or DMA Controller. They also may be driven by other microprocessors or DMA controllers that reside on the I/O channel as bus masters.
/SBHE	101	I/O	PU	System Byte High Enable: A low allows high-byte data transfers on the data bus SD8-SD15. 16-bit devices use this signal to condition data bus buffers tied to SD8-SD15. This signal is the output of the /BHE latch.
SD(0-7)	140-133	I/O	PU	System Data bus: For data transfers between the expansion slots and the D bus.
SDDIR	78	O		SD bus DIRection
/SDHE	79	O		SD bus High ENable

\* Indicates Internal Resistor

## HT12 Pin Description

Pin Symbol	Pin Numbers	Pin Type	Pull Up/Dn*	Description
/SMEMR	94	O		System MEMory Read: Low during memory reads in the low 1 MB of memory space. It instructs the memory device to drive data onto the data bus. Not active during local memory accesses or accesses above 1 MB.
/SMEMW	93	O		System MEMory Write: Low during memory writes within the low 1 MB of memory space. It instructs the memory device to store the data present on the data bus. Not active during local memory accesses or accesses above 1 MB.
SPKR	77	O		SPEaKeR: Output of the Timer 8254 Channel 2. This connects to a speaker, through a buffer.
SYSCLK	12	O		SYStem CLocK: This provides a clock for devices on the expansion slot. SYSCLK is constant at one fourth the CLKASN frequency.
TC	116	I/O	PD	Terminal Count: TC pulses high when the DMA channel terminal count is reached. This signal is available on the expansion slot. Also used as power up configuration input pin.
XDDIR	81	O		XD bus DIRection

\*Indicates Internal Resistor

## HT12 Pin Description

Pin Symbol	Pin Numbers	Pin Type	Pull Up/Dn*	Description
/OWS	89	I	PU	Zero Wait State: This signal tells the microprocessor that it can complete the present bus cycle without inserting additional wait cycles. It comes from an address decode gated with a Read/Write command. In order to run a memory cycle to an 8-bit device with a minimum of 2 wait states, OWS must be driven low one system clock after Read or Write command is gated with the address decode for the device. These Read/Write commands are active on the falling edge of the system clock. This signal should be driven by an open collector or tri-state driver capable of sinking 20mA. Should be connected to external 300 Ohm pull up.
VDD	10,40,80,120, 151,160			Power: +5 Volts Supply
VSS	1,17,41,59,99, 145			Ground

\* Indicates Internal Resistor

To be added in the next revision of this document.

Preliminary Timing

Unspecified output pins have 65pF loading

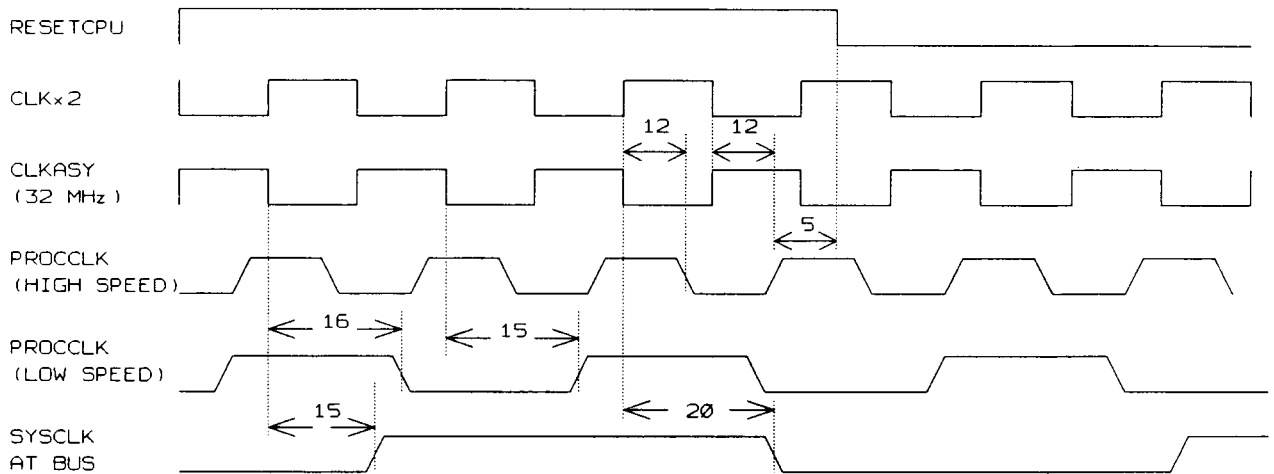
Unspecified bi-directional pins have 100pF loading

D0-D15	100pF load;	TTL-level
MA0-MA9	250pF load;	TTL-level
/RAS0,/RAS1	150pF load;	TTL-level
/CASL0,/CASL1	100pF load;	TTL-level
/MWE	300pF load;	TTL-level
PROCCLK	50pF load;	TTL-level
/READY	50pF load;	TTL-level
MDPH	50pF load;	TTL-level
MDPL	50pF load;	TTL-level

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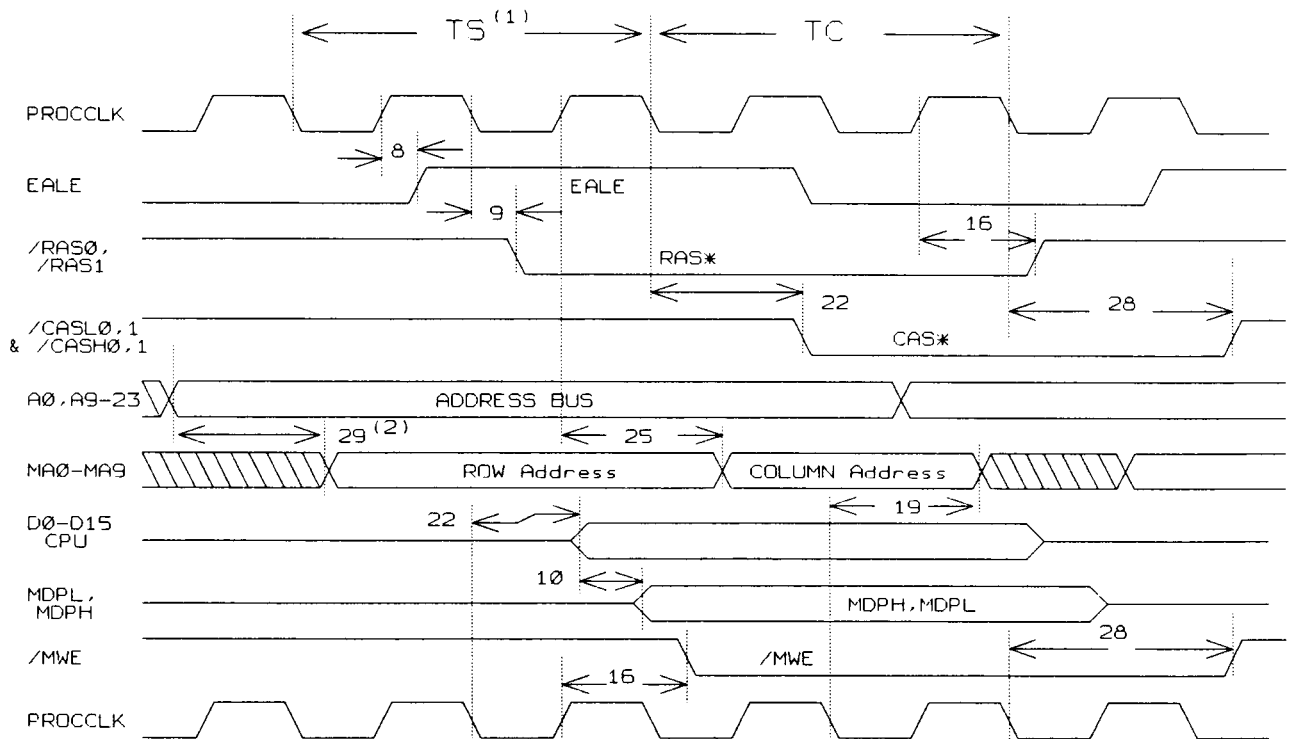
**CLOCK TIMING**  
**Figure 1**

**Max Timing**



**ZERO WAIT STATE MEMORY CYCLE**  
**Figure 2A**

Max Timing



PROCCLK MUST HAVE A 50% DUTY CYCLE

Note: All DRAM timings that reference PROCCLK assume a 50pF load on PROCCLK.

NOTE1: TS = 80.0ns at 12.5 MHz  
TS = 62.5ns at 16.0 MHz

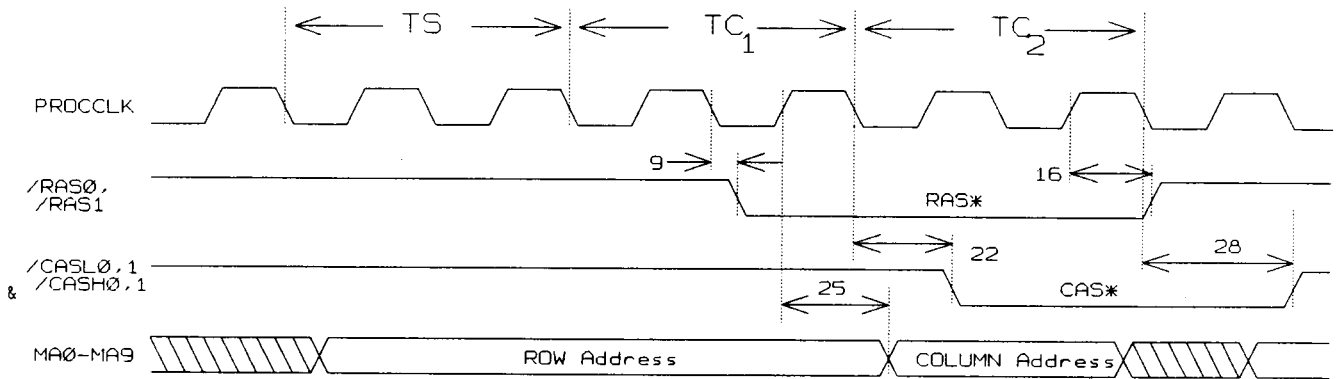
Note 2: 29ns REGULAR or RELOCATED Cycles  
35ns with EMS Cycles  
37ns with EMS RELOCATED Cycles



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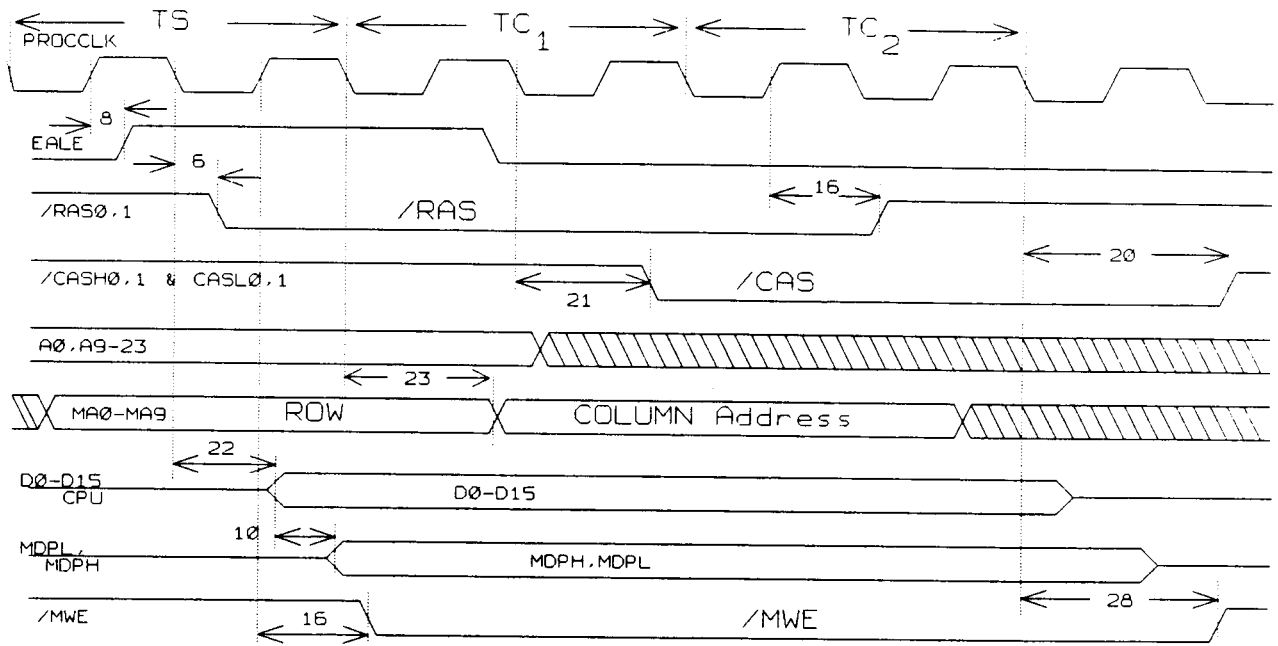
**ZERO WAIT-STATE MEMORY CYCLE WITH 1 EXTRA WAIT- STATE**  
**Figure 2B**

Max Timing



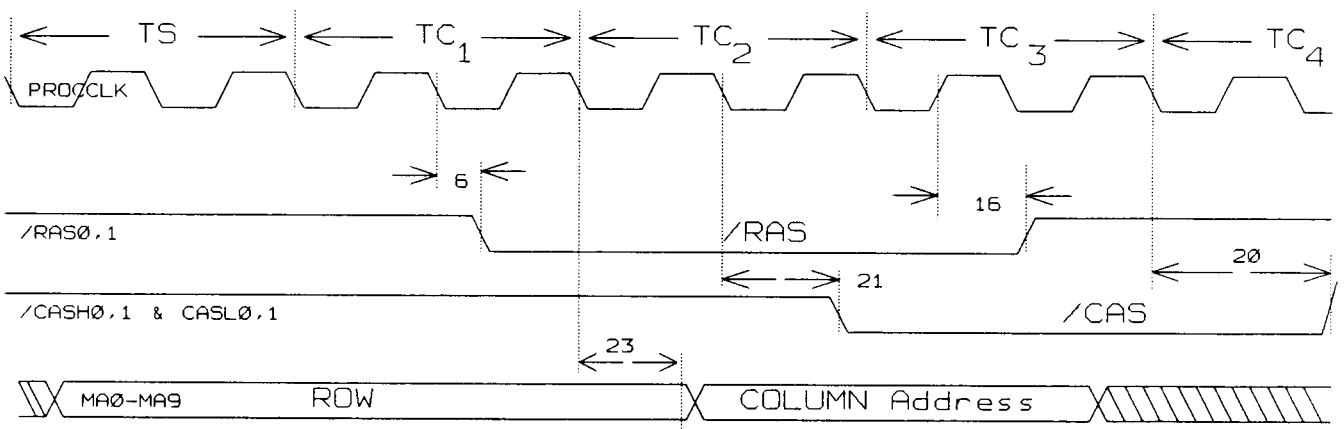
ONE WAIT- STATE MEMORY CYCLE  
Figure 3A

Max Timing



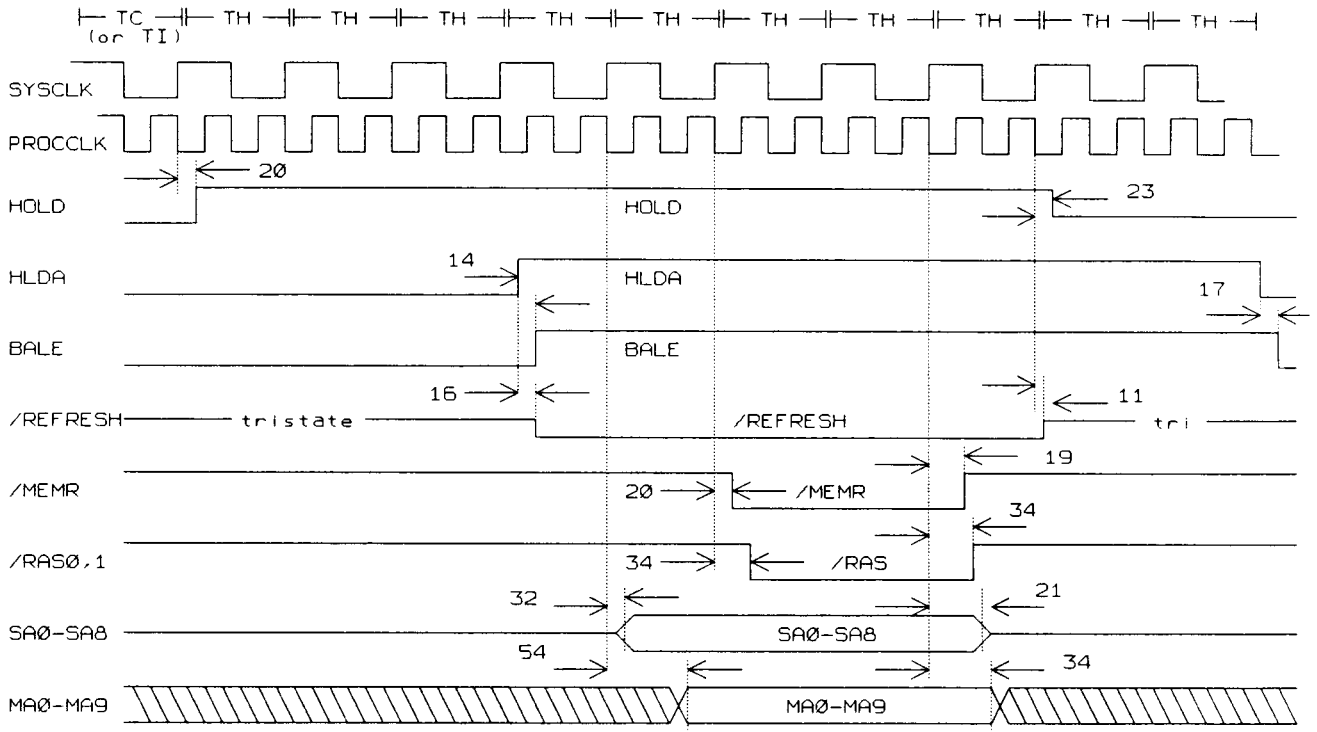
**ONE WAIT- STATE MEMORY CYCLE WITH 1 EXTRA WAIT- STATE**  
**Figure 3B**

Max Timing



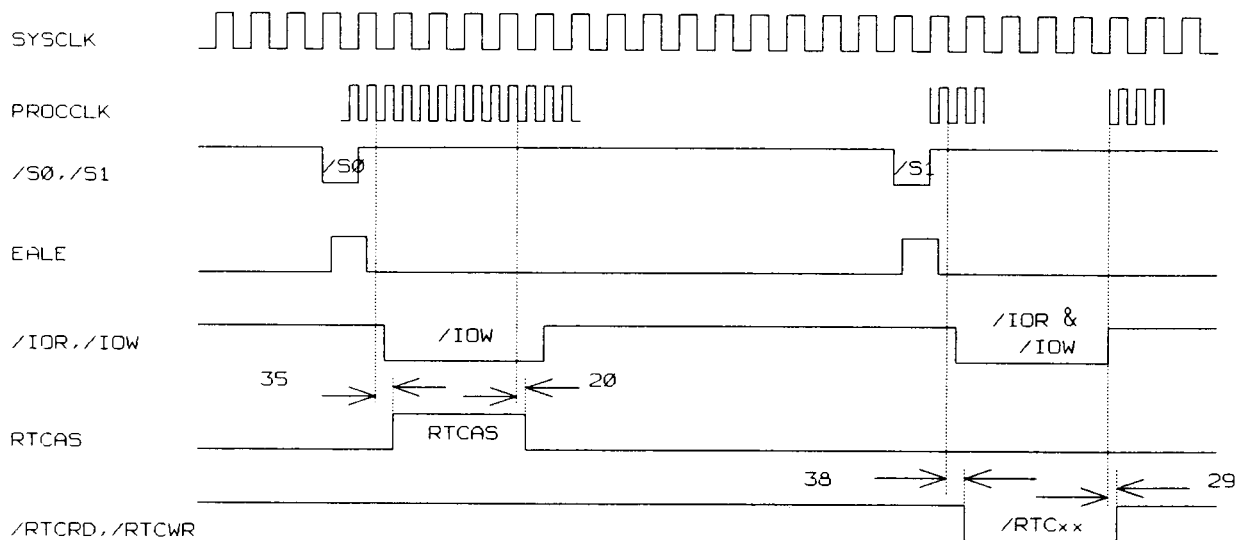
**REFRESH**  
**Figure 4**

Max Timing



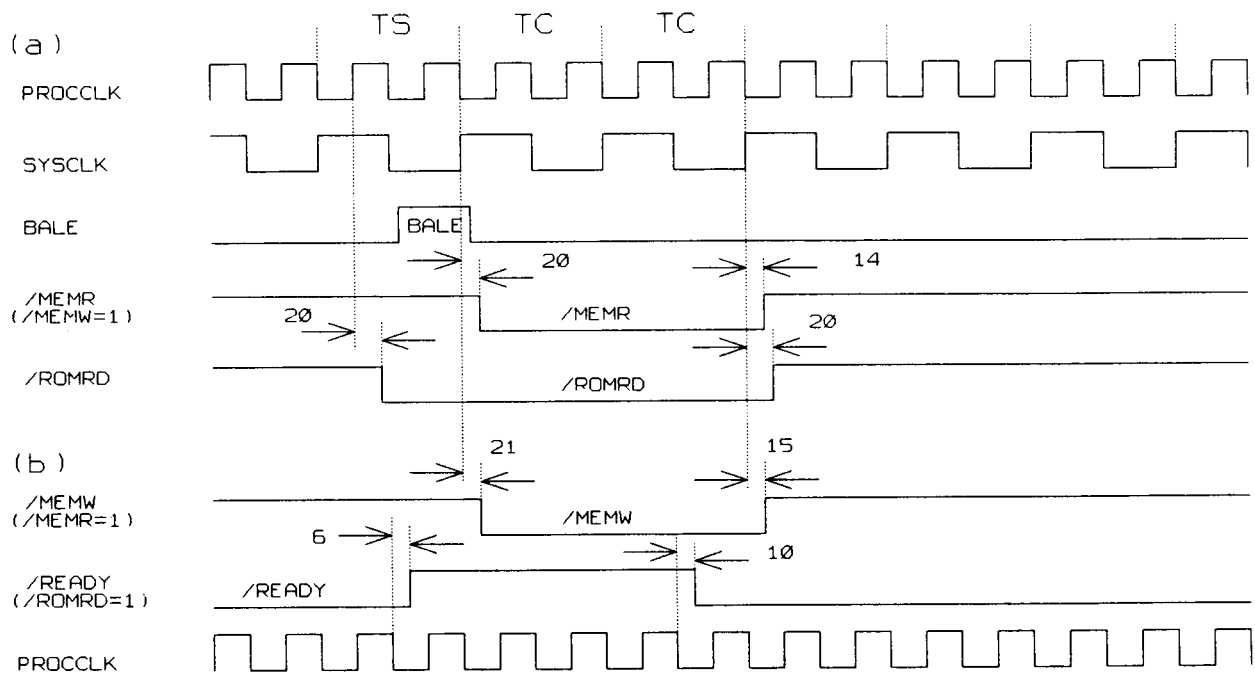
REAL TIME CLOCK TIMING  
Figure 5

Max Timing



a) ROM READ  
b) 16-BIT MEMR TO 16-BIT DEVICES  
Figure 6

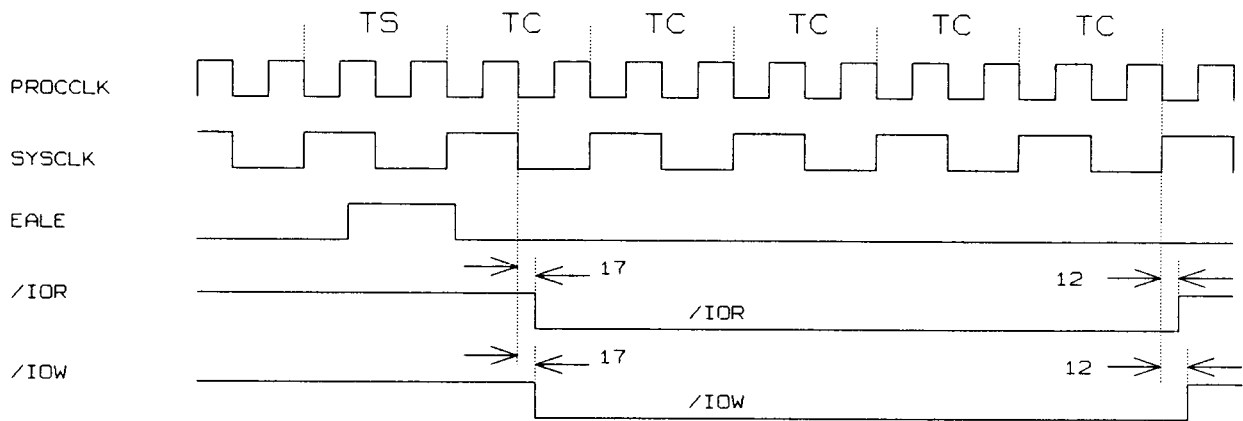
Max Timing



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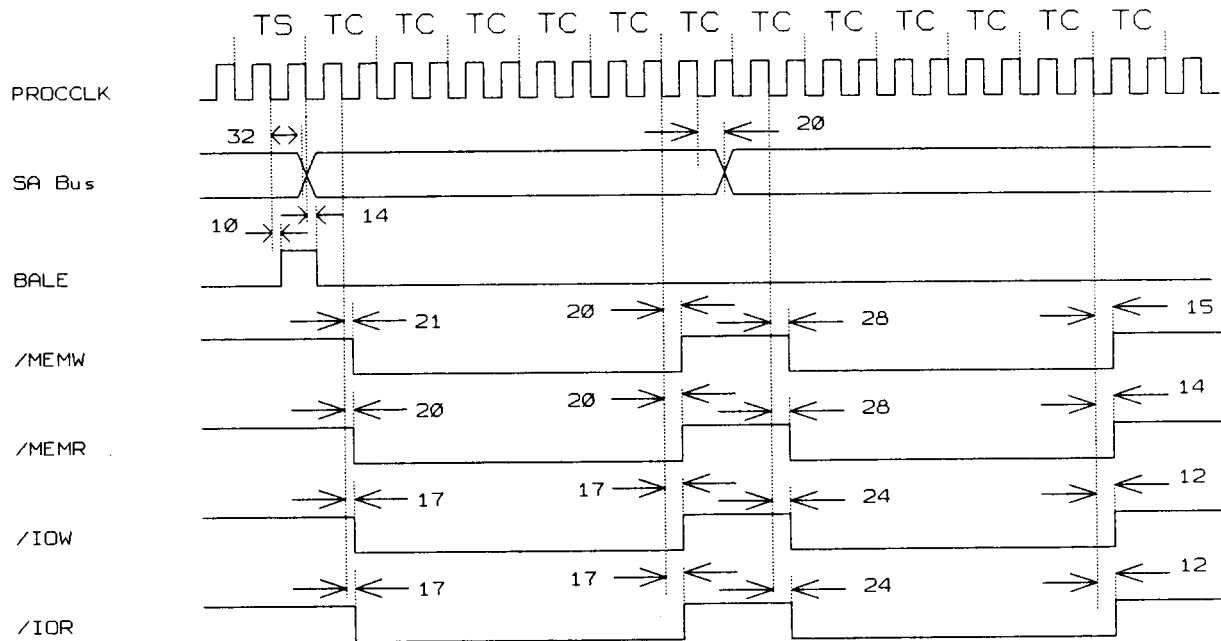
**8-BIT /IOR AND /IOW**  
**Figure 7**

Max Timing



**16-BIT /MEMR, /MEMW AND /IOR, /IOW TO 8-BIT DEVICES**  
**Figure 8**

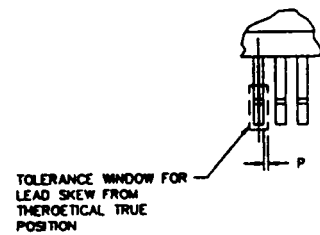
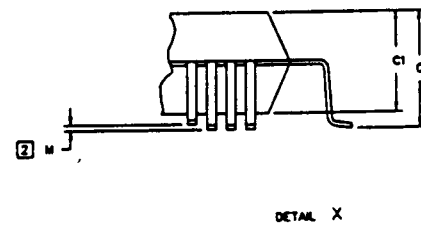
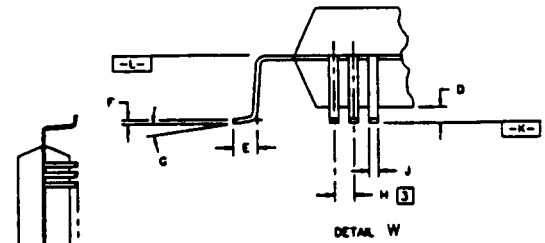
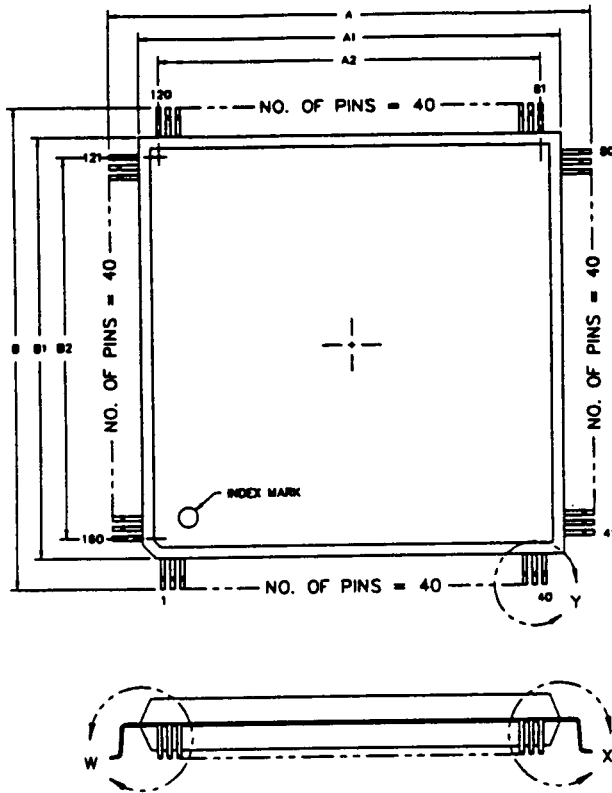
Max Timing





# HT12 Package Outline

## 160-Pin Flat Pack (Gull Wing)



NOTES: UNLESS OTHERWISE SPECIFIED

- 1 NOMINAL DIMENSIONS IN MILLIMETERS. INCHES ROUNDED TO THE NEAREST .001 INCH.
- 2 COPLANARITY OF ALL LEADS SHALL BE WITHIN 0.1 MM (0.004") (DIFFERENCE BETWEEN HIGHEST AND LOWEST LEAD WITH SEATING PLANE [K] AS REFERENCE)
- 3 LEAD PITCH DETERMINED AT DATUM [X]
- 4 CONTROLLING DIMENSIONS ARE IN MILLIMETERS.

1

DIMENSIONS IN MM		
SYM	MINIMUM	MAXIMUM
A	31.80	32.40
A1	27.90	28.10
A2	25.35 REF	
B	31.80	32.40
B1	27.90	28.10
B2	25.35 REF	
C	3.68	4.01
C1	3.43	3.68
D	0.25	0.36
E	0.60	1.00
F	0.10	0.25
G	0"	10"
H	0.85 ±0.15	
J	0.25	0.35
M	0.10 MAX	
P	0.05 MAX	
TOTAL NO. OF PINS	160	

1

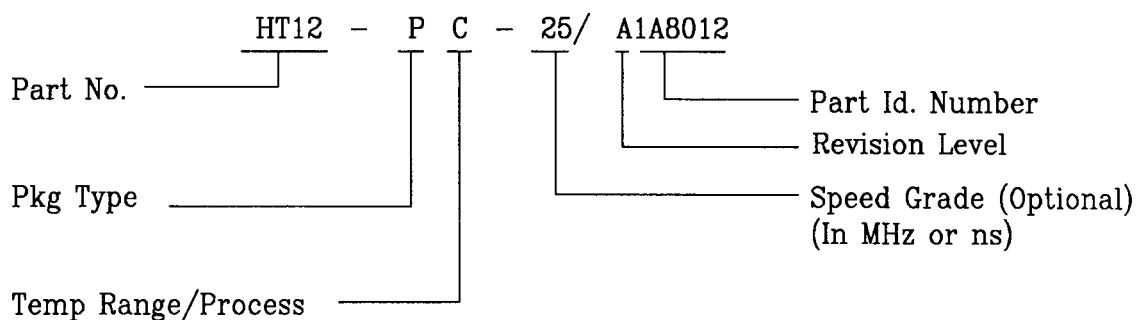
DIMENSIONS IN INCHES		
SYM	MINIMUM	MAXIMUM
A	1.244	1.278
A1	1.098	1.108
A2	0.998 REF	
B	1.244	1.278
B1	1.098	1.108
B2	0.998 REF	
C	0.145	0.158
C1	0.135	0.144
D	0.010	0.014
E	0.024	0.039
F	0.004	0.010
G	0"	10"
H	0.028 ±0.008	
J	0.010	0.014
M	0.004 MAX	
P	0.002 MAX	
TOTAL NO. OF PINS	160	

### IMPORTANT NOTE:

If designing in inches, ALL pin positions should be calculated in millimeters (mm) then converted to inches. The inches listed have been rounded.

Product Ordering Information & Part Marking

Order Code/Part Number Example



Temp Range/Process

C – Commercial temp range (0°C to 70°C)

Package Types

P – Plastic

**IMPORTANT:** Contact your local sales office for the current Order Code/Part Number

## Sales Representatives

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#### UNIAO DIGITAL

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**Fax 415-656-0397**

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